



HP SSD EX900 M.2

Product Specification

Capacity: 120GB, 250GB, 500GB

Components: 3D NAND TLC

Read and Write IOPS

(Iometer* Queue Depth 32)

—120 GB

Random 4 KB reads: Up to 110 K IOPS

Random 4 KB writes: Up to 100 K IOPS

— 250 GB

Random 4 KB reads: Up to 120 K IOPS

Random 4 KB writes: Up to 105 K IOPS

—500 GB

Random 4 KB reads: Up to 120 K IOPS

Random 4 KB writes: Up to 108 K IOPS

Bandwidth Performance

— 120 GB

Sustained sequential read: Up to 1900 MB/s

Sustained sequential write: Up to 650 MB/s

— 250 GB

Sustained sequential read: Up to 2100 MB/s

Sustained sequential write: Up to 1300 MB/s

— 500 GB

Sustained sequential read: Up to 2100 MB/s

Sustained sequential write: Up to 1500 MB/s

PCIe Gen 3(8Gb/s) x 4, NVMe 1.3 interface

— Compliant with PCI-Express 3.1

— Dual ARM Cortex R5 CPU @ 5000Hz

— NVMe 1.3 register interface and
command set

— Data set management command

Trim attribute

Form Factor: Full-sized M.2 2280 SSD

— Dimensions: 80 mm x 22 mm

— Thickness: <=2.4 mm

— Weight: <=5.4 grams

Power Management

— 3.3V M.2 SSD power supply

—M.2 SSD interface power management

Power (Mobile Mark* 2007 Workload)

— Idle: 680 mW (TYP)

— max: 3.52 W (TYP)

Temperature

— Operating: 0°C to 70°C

— Non-Operating: -40°C to 85°C

Shock (operating and non-operating)

— 100 G/6 msec

Vibration(operating and non-operating)

—3.1G RMS (2-500 Hz)



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Latency

— 120 GB

Read: 0.031ms (TYP)

Write: 0.043ms (TYP)

—250 GB

Read: 0.028ms (TYP)

Write: 0.035ms (TYP)

—500 GB

Read: 0.021ms (TYP)

Write: 0.029ms (TYP)

Reliability

— Uncorrectable Bit Error Rate (UBER):
1 sector in 10^{16} bits read

— Mean Time Between Failures (MTBF):
2,000,000 hours

Certifications and Declarations

— CB

— cTUVus & FCC

— CE & RoHS

— BSMI & KCC & VCCI

Order Information

Country/Region	PN	Capacity
APJ	2YY42AA#UUF	120GB
	2YY43AA#UUF	250GB
	2YY44AA#UUF	500GB
NA	2YY42AA#ABC	120GB
	2YY43AA#ABC	250GB
	2YY44AA#ABC	500GB
EURO	2YY42AA#ABB	120GB
	2YY43AA#ABB	250GB
	2YY44AA#ABB	500GB
LA	2YY42AA#ABL	120GB
	2YY43AA#ABL	250GB
	2YY44AA#ABL	500GB



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1.0 Overview

HP SSD EX900 M.2 Series delivers compact storage and optimized performance for traditional and innovative small-form-factor and embedded platforms in 3 capacity sizes: 120GB , 250GB and 500GB.

By combining advanced NAND Flash controller with PCIe Gen 3(8Gb/s) x 4, NVMe 1.3 interface and 3D NAND Flash, PCIe M.2 delivers sequential read speed up to 2100MB/s and sequential write speed up to 1500MB/s, which makes it a ideal solution for computing device, such as, notebook, thin-and-light systems, mini- and sub-notebooks, all in-one computers, and embedded platforms.

As compared to standard mobile HDDs, HP SSD EX900 M.2 Series offers these key features:

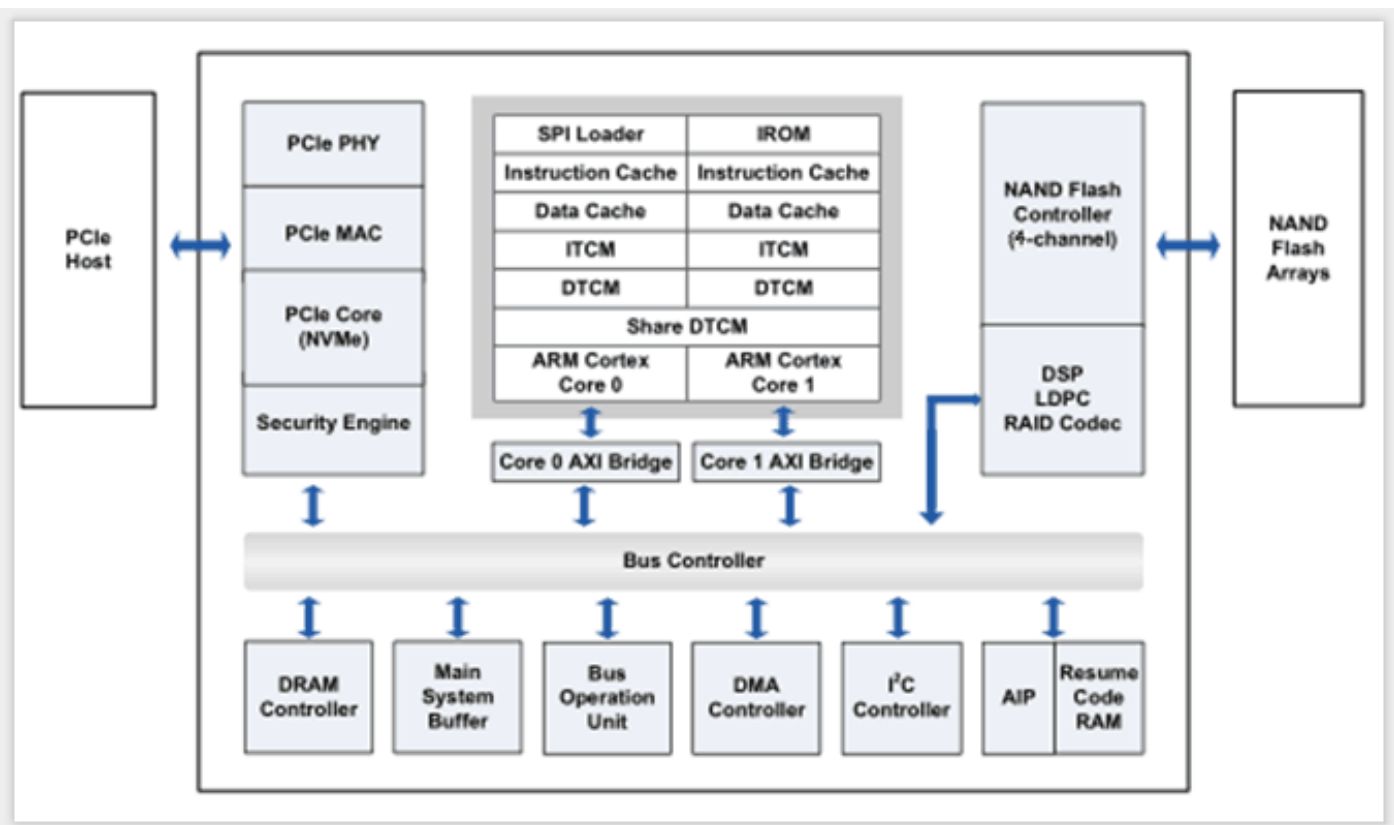
- High performance
- Low power
- Increased system responsiveness
- High reliability
- Small form-factor
- Minimum weight
- Enhanced ruggedness
- High data Integrity and Security



2.0 Architecture

HP SSD EX900 M.2 Series utilizes a cost-effective, high-performance HP PCIe-to-NAND controller to manage a full PCIe Gen 3(8Gb/s) x 4 bandwidth with the host while managing multiple NAND flash memory devices on 4 channels.

Figure 1. Block Diagram





3.0 Product Specifications

This section provides details on HP SSD EX900 M.2 Series product specifications.

3.1 Capacity

Table 1. User Addressable Sectors

Unformatted Capacity	120GB	250GB	500GB
Total User Addressable Sectors	234,430,402	488,396,671	976,793,343

Notes: LBA count shown represents total user storage capacity and will remain the same throughout the life of the drive.

The total usable capacity of the SSD may be less than the total physical capacity because a small portion of the capacity is reserved for NAND flash management and maintenance purposes.

1 GB = 1,000,000,000 bytes; 1 sector = 512 bytes.

3.2 Performance

Table 2. Read/Write IOPS, Bandwidth, Latency

Performance	120GB	250GB	500GB
Random Read/Write IOPS (Input / Output Operations per Second)(1)			
4K Read (Up to)	110,000	120,000	120,000
4K Write (Up to)	100,000	105,000	110,000
Maximum Sustained Read and Write Bandwidth(2)			
Sequential Read (Up to)	1900 MB/s	2100 MB/s	2100 MB/s
Sequential Write (Up to)	650 MB/s	1300 MB/s	1500 MB/s
Latency(3)			
Read	0.031 ms	0.028 ms	0.021 ms
Write	0.043 ms	0.035 ms	0.029 ms



Notes:

(1). Performance measured using Iometer with queue depth set to 32; Measurements are performed on 8 GB of LBA range. Write Cache enabled.

(2). Performance measured using Iometer with queue depth equal to 32.

Sequential performance measurements assume 1 MB/sec = 1,048,576 bytes/sec.

(3). Device measured using Iometer; Read/Write latency measured on sequential 4 K transfers with queue depth set to 1.

Write Cache Enabled.

Power On To Ready time measured from power rail rising edge to the first DRDY issued from the drive.



3.3 Electrical

Table 3. Operating Voltage and Power Consumption

Electrical Characteristics	120GB	250GB	500GB
Operating Voltage for 3.3V (+/- 5%)			
Min		3.14 V	
Max		3.47 V	
Power Consumption (Typical)			
Active1	2.46 W	2.99 W	3.52 W
Idle	0.68 W	0.68 W	0.68 W

Notes:

1. Active power measured during execution of MobileMark* 2007 with DIPM (Device Initiated Power Management) enabled.
2. Idle power defined as SSD at idle with DIPM enabled.



3.4 Environmental Conditions

Table 4. Temperature, Shock, Vibration

Temperature	Range
Ambient Temperature	
Operating	0 to 70 °C
Non-operating	-40 to 85 °C
Temperature Gradient(1)	
Operating	20 (Typical) °C/hr
Non-operating	30 (Typical) °C/hr
Humidity	
Operating	5 - 95 %
Non-operating	5 - 95 %
Shock, Vibration, Acoustics	Range
Shock(2)	
Operating	100 G/6 msec
Non-operating	100 G/6 msec
Vibration(3)	
Operating	3.1 GRMS (2-500 Hz)
Non-operating	3.1 GRMS (2-500 Hz)

Notes:

(1). Temperature gradient measured without condensation.

(2). Shock specifications assume the SSD is mounted securely with the input vibration applied to the drive-mounting screws. Stimulus may be applied in the X, Y or Z axis. Shock specification is measured using root mean square (RMS) value.

(3). Vibration specifications assume the SSD is mounted securely with the input vibration applied to the drive-mounting screws.

Stimulus may be applied in the X, Y or Z axis. The measured specification is in root mean squared form. Vibration specification is measured using RMS value.



3.5 Reliability

Table 5. Reliability Specifications

Parameter	Value
<p>Uncorrectable Bit Error Rate (UBER)</p> <p>Unrecoverable read bit error rate will not exceed one sector in the specified number of bits read. In the extremely unlikely event of a no recoverable read error, the SSD will report it as a read failure to the host; the sector in error is considered corrupt and is not returned to the host.</p>	1 sector in 10^{16} bits read, max
<p>Mean Time Between Failure (MTBF)</p> <p>Mean time between failures (MTBFs) for the SSD can be predicted based on the component reliability data using the methods referenced in the Telcordia SR-332 reliability prediction procedures for electronic equipment.</p>	2,000,000 hours
<p>Power On/Off Cycles</p> <p>Power On/Off Cycles is defined as power being removed from HP SSD EX900 M.2, and then restored. Most host systems remove power from the SSD when entering suspend and hibernate as well as on a system shutdown.</p>	10,000 cycles
<p>Minimum Useful Life</p> <p>HP SSD EX900 M.2 will have a minimum of three years of useful life under typical client workloads with up to 80% of the full capacity of host writes per day.</p>	3 years



4.0 Mechanical Information

Figure 2 shows the physical dimension of HP SSD EX900 M.2 Series.

All dimensions are in millimeters.

Figure 2. HP SSD EX900 M.2 Dimensions

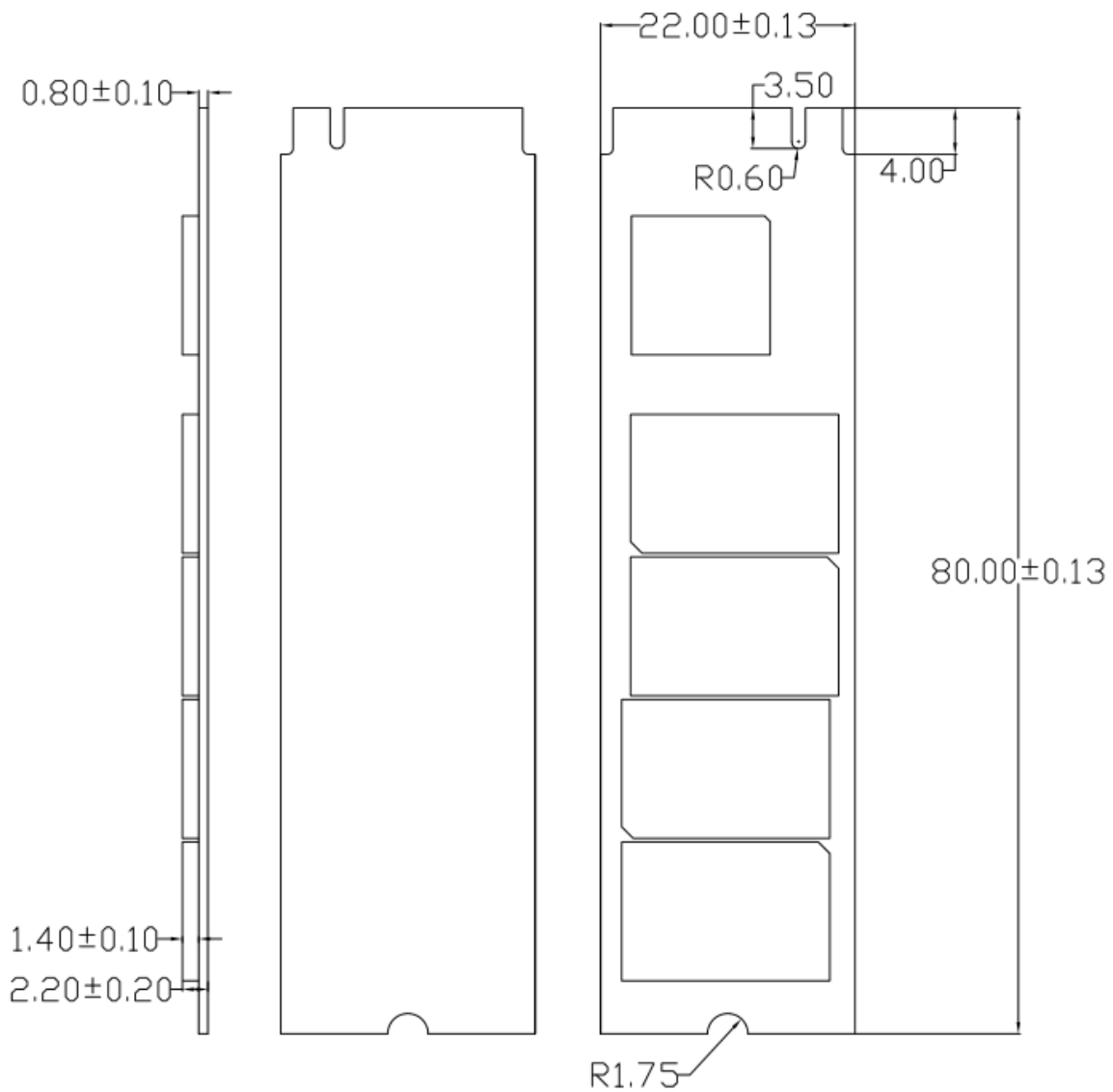
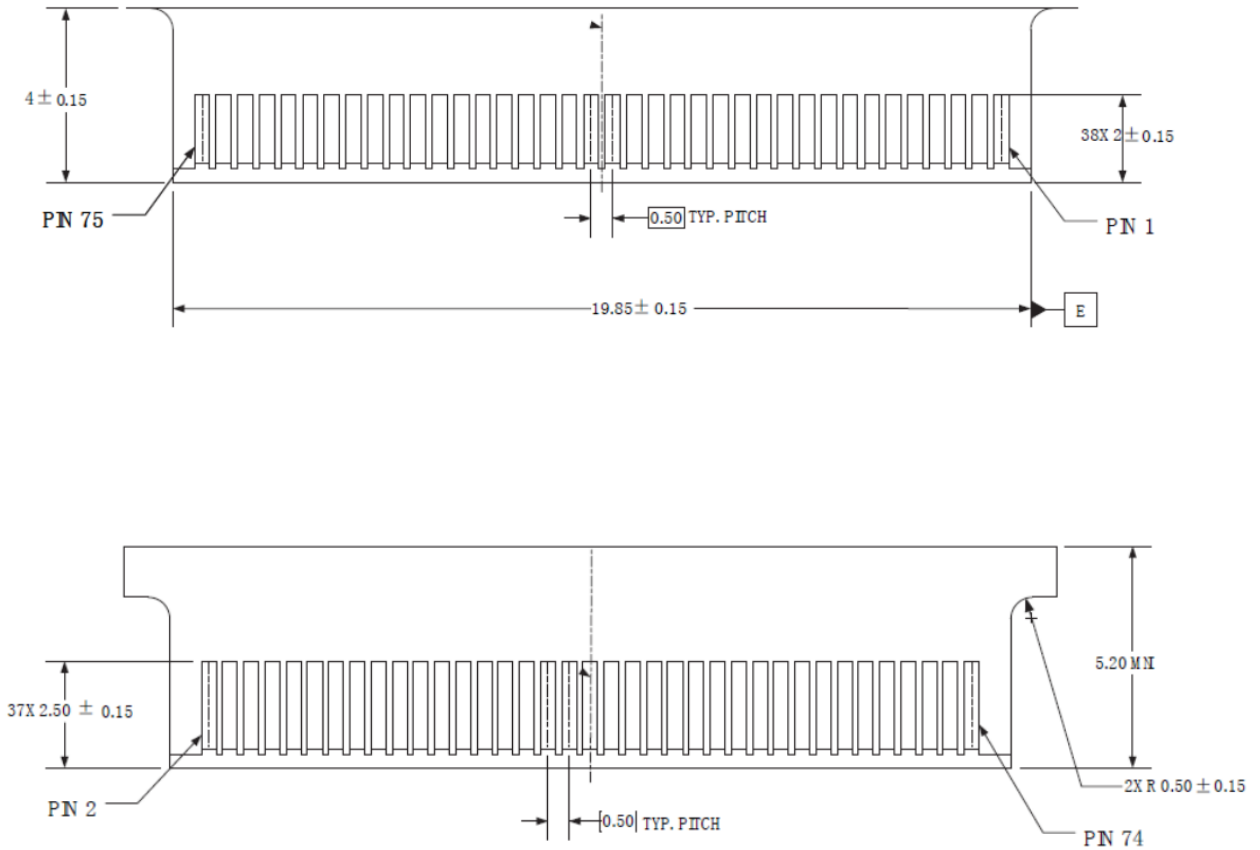




Figure 3. HP SSD EX900 M.2 Interface Description





5.0 Pin and Signal Descriptions

5.1 Pin Locations

Pin#	Assignment	Description	Pin#	Assignment	Description
1	CONFIG_3	Defines module type	21	CONFIG_0	Defines module type
2	+3.3V	3.3V source	22	NA	NA
3	GND	Return Current Path	23	NA	NA
4	+3.3V	3.3V source	24	NA	NA
5	NA	NA	25	NA	NA
6	NA	NA	26	NA	NA
7	NA	NA	27	GND	Return Current Path
8	NA	NA	28	NA	NA
9	NA	NA	29	NA	NA
10	NA	NA	30	NA	NA
11	NA	NA	31	NA	NA
12	(removed for key)	Mechanical Notch B	32	NA	NA
13	(removed for key)	Mechanical Notch B	33	GND	Return Current Path
14	(removed for key)	Mechanical Notch B	34	NA	NA
15	(removed for key)	Mechanical Notch B	35	NA	NA
16	(removed for key)	Mechanical Notch B	36	NA	NA
17	(removed for key)	Mechanical Notch B	37	NA	NA
18	(removed for key)	Mechanical Notch B	38	DEVSLP	Device Sleep, Input
19	(removed for key)	Mechanical Notch B	39	GND	Return Current Path
20	NA	NA	40	NA	NA

Table 6.Connector Pin Signal Definitions



5.2 Signal Descriptions

Pin#	Assignment	Description	Pin#	Assignment	Description
41	PCIe-B+/PERn0	Host receiver differential signal pair	61	NOTCH	Mechanical Notch M
42	NA	NA	62	NOTCH	Mechanical Notch M
43	PCIe-B-/PERp0	Host receiver differential signal pair	63	NOTCH	Mechanical Notch M
44	NA	NA	64	NOTCH	Mechanical Notch M
45	GND	Return Current Path	65	NOTCH	Mechanical Notch M
46	NA	NA	66	NOTCH	Mechanical Notch M
47	PCIe-A-/PETn0	Host transmitter differential signal pair	67	NA	NA
48	NA	NA	68	NA	NA
49	PCIe-A+/PETp0	Host transmitter differential signal pair	69	CONFIG_1	Defines module type
50	NA	NA	70	+3.3V	3.3V source
51	GND	Return Current Path	71	GND	Return Current Path
52	NA	NA	72	+3.3V	3.3V source
53	NA	NA	73	GND	Return Current Path
54	NA	NA	74	+3.3V	3.3V source
55	NA	NA	75	CONFIG_2	Defines module type
56	NA	NA			
57	GND	Return Current Path			
58	NA	NA			
59	NOTCH	Mechanical Notch M			
60	NOTCH	Mechanical Notch M			



6.0 Supported Command Sets

HP SSD EX900 M.2 Series supports PCIe (PCI-express) commands described in this section.

6.1 PCIe General Feature Command Set

HP SSD EX900 M.2 Series supports the PCIe General Feature command set (non-PACKET), which consists of:

- EXECUTE DEVICE DIAGNOSTIC
- FLUSH CACHE
- IDENTIFY DEVICE
- READ DMA
- READ SECTOR(S)
- READ VERIFY SECTOR(S)
- SEEK
- SET FEATURES
- WRITE DMA
- WRITE SECTOR(S)
- READ MULTIPLE
- SET MULTIPLE MODE
- WRITE MULTIPLE

HP SSD EX900 M.2 Series also supports the following optional commands:

- READ BUFFFER
- WRITE BUFFER
- NOP
- DOWNLOAD MICROCODE



6.2 Power Management Command Set

HP SSD EX900 M.2 Series supports the Power Management command set, which consists of:

- CHECK POWER MODE
- IDLE
- IDLE IMMEDIATE
- SLEEP
- STANDBY
- STANDBY IMMEDIATE

6.3 Security Mode Feature Set

HP SSD EX900 M.2 Series supports the Security Mode command set, which consists of:

- SECURITY SET PASSWORD
- SECURITY UNLOCK
- SECURITY ERASE PREPARE
- SECURITY ERASE UNIT
- SECURITY FREEZE LOCK
- SECURITY DISABLE PASSWORD



6.4 smart Command Set

HP SSD EX900 M.2 Series supports the SMART command set, which consists of:

- SMART ENABLE OPERATIONS
- SMART DISABLE OPERATIONS
- SMART ENABLE/DISABLE AUTOSAVE
- SMART RETURN STATUS

HP SSD EX900 M.2 Series also supports the following optional commands:

- SMART EXECUTE OFF-LINE IMMEDIATE
- SMART READ DATA
- SMART READ LOG
- SMART WRITE LOG

6.5 Data Set Management Command Set

HP SSD EX900 M.2 Series supports the Data Set Management command set Trim attribute, which consists of:

- DATA SET MANAGEMENT EXT



6.6 Host Protected Area Command Set

HP SSD EX900 M.2 Series supports the Host Protected Area command set:

- READ NATIVE MAX ADDRESS
- SET MAX ADDRESS
- READ NATIVE MAX ADDRESS EXT
- SET MAX ADDRESS EXT

HP SSD EX900 M.2 Series also supports the following optional commands:

- SET MAX SET PASSWORD
- SET MAX LOCK
- SET MAX FREEZE LOCK
- SET MAX UNLOCK

6.7 48-Bit Address Command Set

HP SSD EX900 M.2 Series supports the 48-bit Address command set, which consists of:

- FLUSH CACHE EXT
- READ DMA EXT
- READ NATIVE MAX ADDRESS EXT
- READ SECTOR(S) EXT
- READ VERIFY SECTOR(S) EXT
- SET MAX ADDRESS EXT
- WRITE DMA EXT
- WRITE MULTIPLE EXT
- WRITE SECTOR(S) EXT
- WRITE UNCORRECTABLE EXT



6.8 Device Configuration Overlay Command Set

HP SSD EX900 M.2 Series supports the Device Configuration Overlay command set, which consists of:

- DEVICE CONFIGURATION FREEZE LOCK
- DEVICE CONFIGURATION IDENTITY
- DEVICE CONFIGURATION RESTORE
- DEVICE CONFIGURATION SET

6.9 General Purpose Log Command Set

The EX900 M.2 Series supports the General Purpose Log command set, which consists of:

- READ LOG EXT
- WRITE LOG EXT

6.10 Native Command Queuing

HP SSD EX900 M.2 Series supports the Native Command Queuing (NCQ) command as

- READ FPDMA QUEUED
- WRITE FPDMA QUEUED

Note: *With* a maximum queue depth equal to 32.

6.11 Software Settings Preservation

HP SSD EX900 M.2 Series supports the SET FEATURES parameter to enable/disable the preservation of software settings.

6.12 Device Initiated Power Management (DIPM)

HP SSD EX900 M.2 Series supports the SET FEATURES parameter to enable Device Initiated Power Management.



7.0 Certifications and Declarations

Table 7 describes the Device Certifications supported by HP SSD EX900 M.2 .

Table 7. Device Certifications and Declarations

Certification	Description
CE Compliant	Indicates conformity with the essential health and safety requirements set out in European Directives Low Voltage Directive and EMC Directive.
UL Certified	Underwriters Laboratories, Inc. Component Recognition UL60950-1.
RoHS Compliant	Restriction of Hazardous Substance Directive

8.0 Revision History

Date	Revision	Description
Nov 2017	V1.0	Initial release
Nov 2017	V2.0	Revise the product's thickness
Nov 2017	V3.0	Updating the Block Diagram
Jan 2018	V4.0	Updating the performance
Mar 2018	V5.0	Updating the Signal Descriptions
July 2018	V6.0	Adding Order information